IN THE DRAWINGS:

The attached sheets of drawings includes changes to Fig. 5 and Fig. 7. These sheets, which include Figs. 1-11B, replace the original sheets including Figs. 1-11B. In Fig. 5, reference numeral reference numeral "152" has been changed to "176," reference number "176" has been changed to "152," and reference numeral "200" has been changed to "213." In Fig. 7, reference numeral "48" has been changed to "748," and reference numeral "717" has been changed to "747." Also in Fig. 5, the position of reference numeral "756" has been moved, and reference numerals "750," "761," and "762: have been added.

Attachment: Replacement Sheet
Annotated Sheet Showing Changes

ANNOTATED SHEET SHOWING CHANGES ATTY DKT, No.: U.S. SERIAL No.:

AMAT/6060/CMP/ECP/RKK

10/043,561 JANUARY 8, 2002

APPLIED MATERIALS, INC. SYSTEM FOR PLANARIZING METAL CONDUCTIVE LAYERS

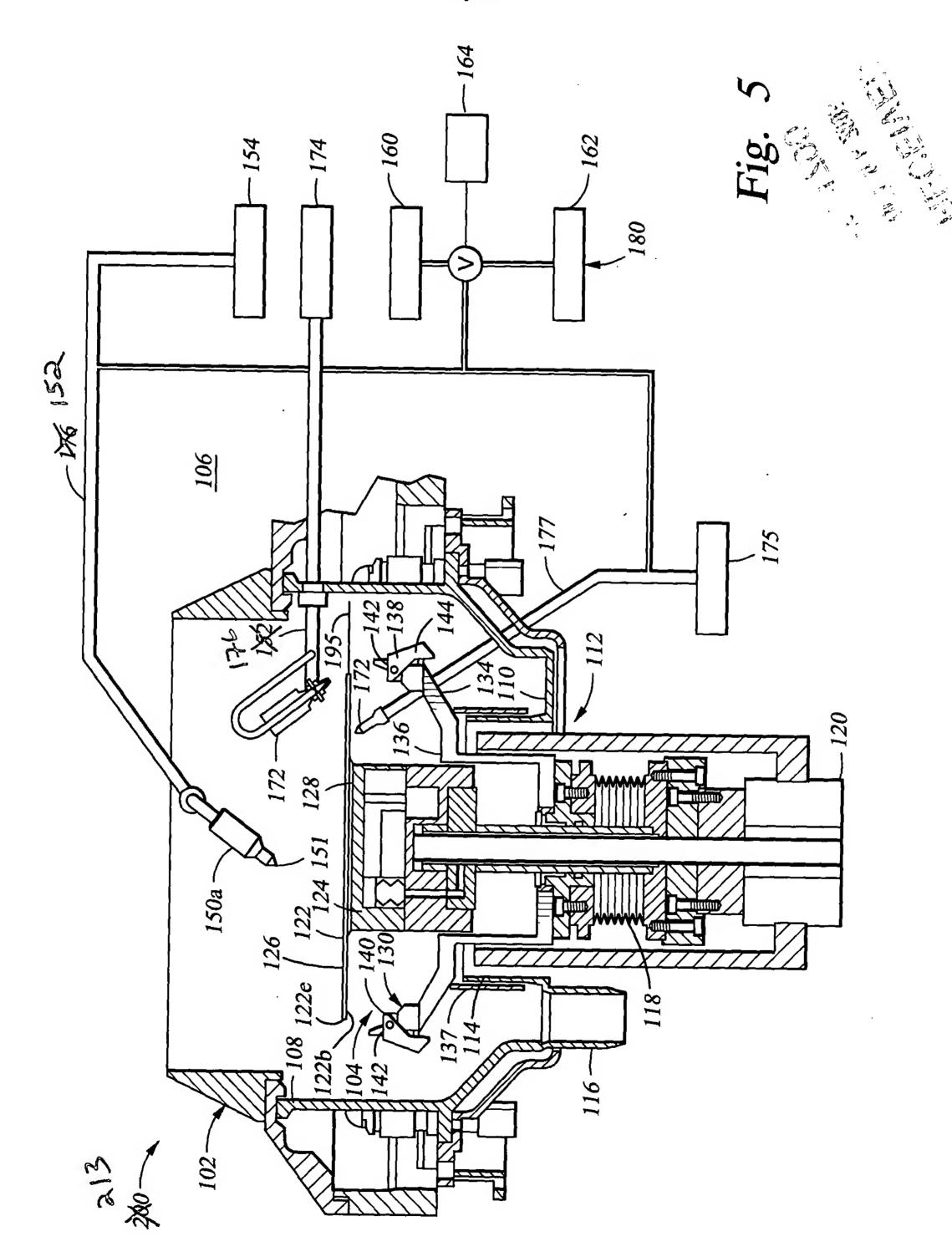
TITLE: INVENTOR: OLGADO, ET AL.

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APPLICANT:

FIGURE 5

CONFIRMATION: 7947





ATTY DKT. No.: U.S. SERIAL No.:

FILED:

APPLICANT: TITLE: INVENTOR:

ANNOTATED SHEET SHOWING CHANGES

AMAT/6060/CMP/ECP/RKK

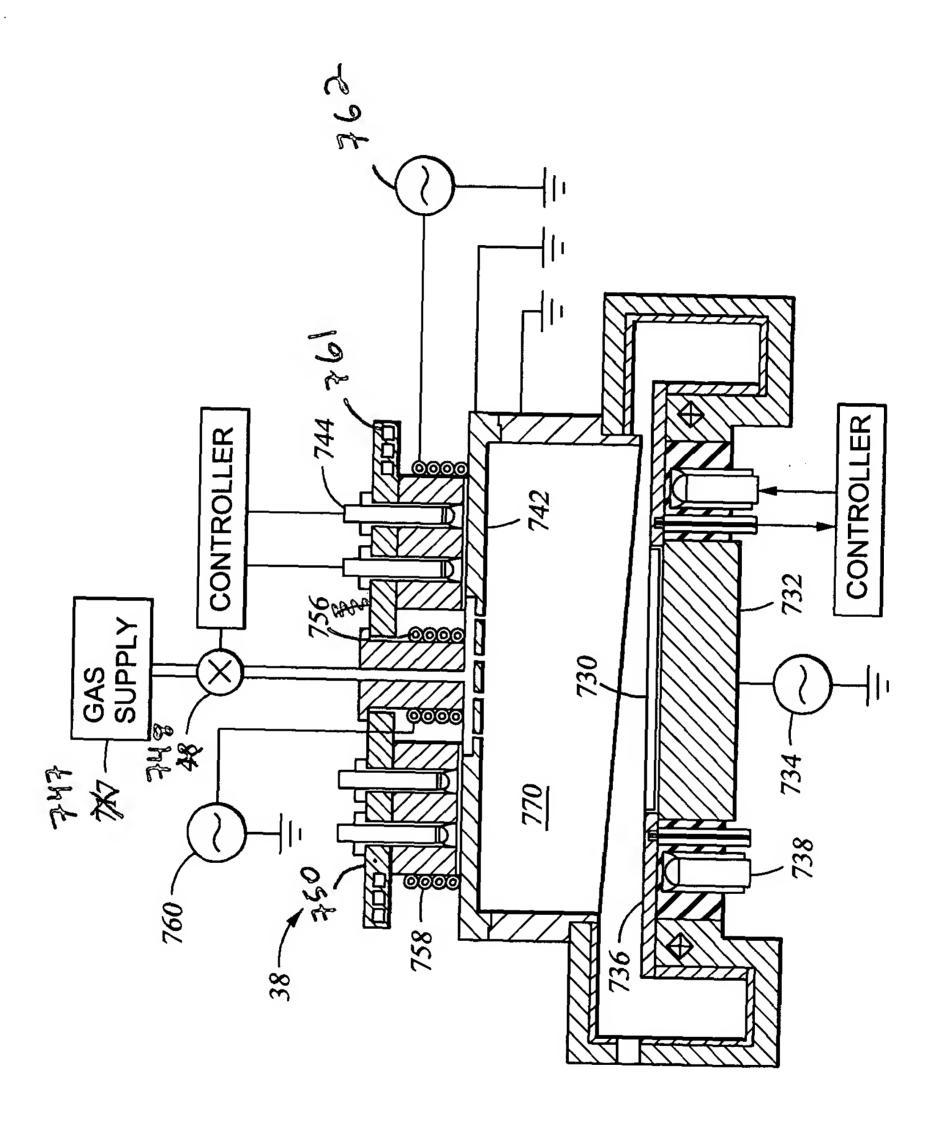
10/043,561 JANUARY 8, 2002 APPLIED MATERIALS, INC.

SYSTEM FOR PLANARIZING METAL CONDUCTIVE LAYERS

OLGADO, ET AL.

FIGURE 7

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- -

REPLACEMENT SHEET

ATTY DKT. No.: AMAT/6060/CMP/ECP/RKK U.S. SERIAL NO.: 10/043,561

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TITLE:

INVENTOR:

JANUARY 8, 2002

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SHEET 1 OF 10

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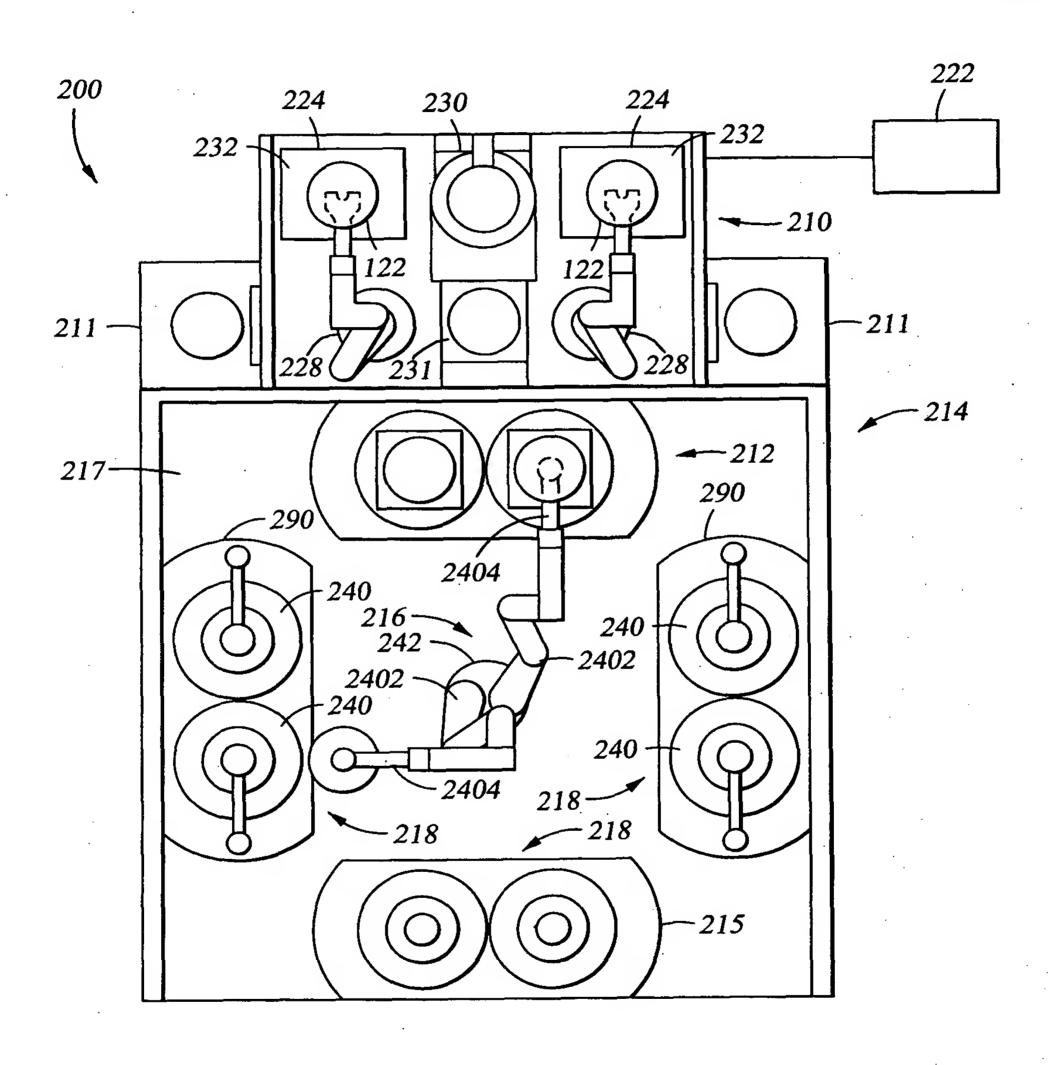


Fig. 1

REPLACEMENT SHEET AMAT/6060/CMP/ECP/RKK

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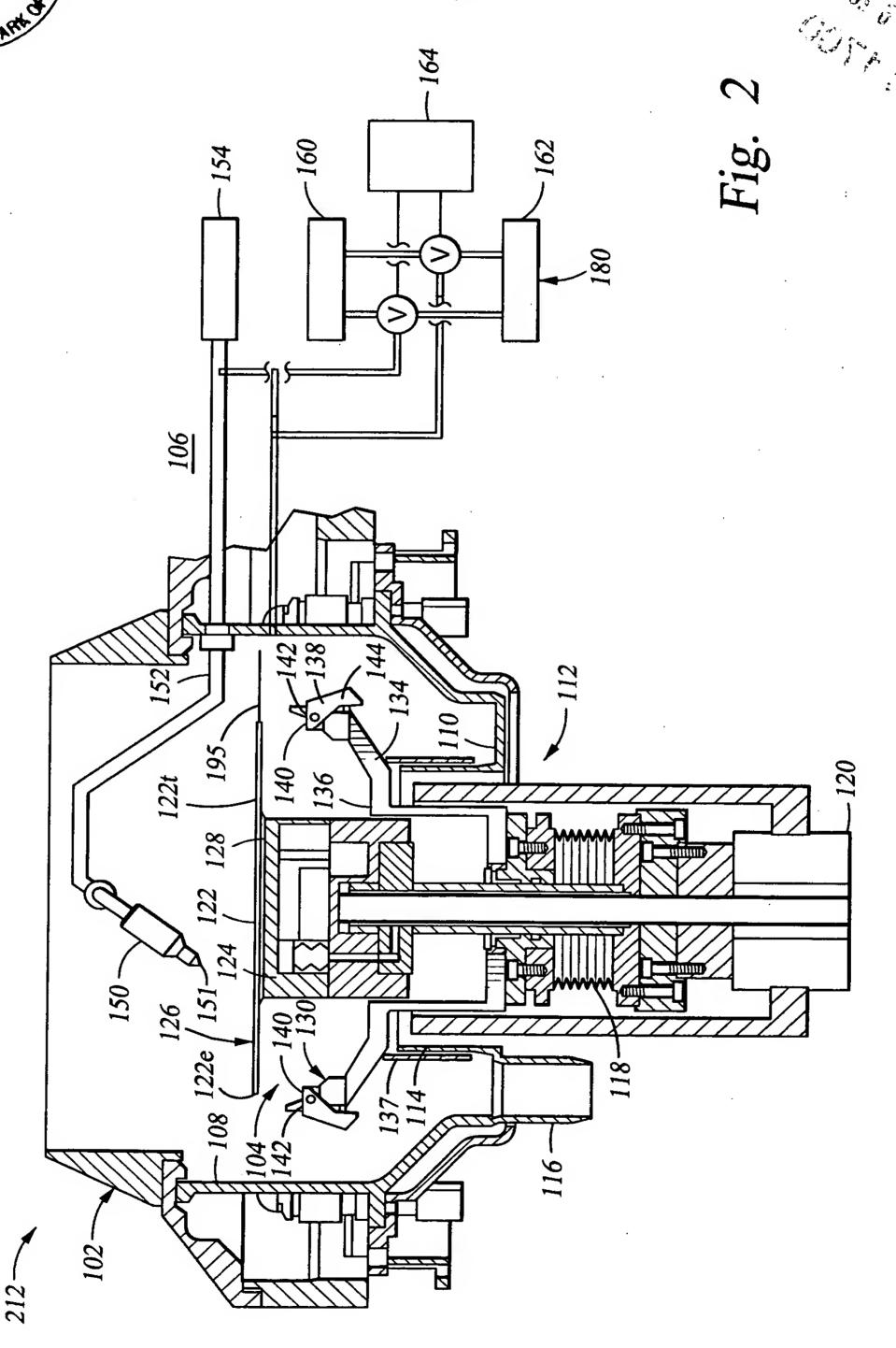
APPLICANT: TITLE: INVENTOR:

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SYSTEM FOR PLANARIZING METAL CONDUCTIVE LAYERS

OLGADO, ET AL.

SHEET 2 OF 10



REPLACEMENT SHEET AMAT/6060/CMP/ECP/RKK

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CONFIRMATION: 7947

FILED: APPLICANT: TITLE:

INVENTOR:

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JANUARY 8, 2002
APPLIED MATERIALS, INC.
System For Planarizing Metal Conductive Layers

OLGADO, ET AL.

SHEET 3 OF 10

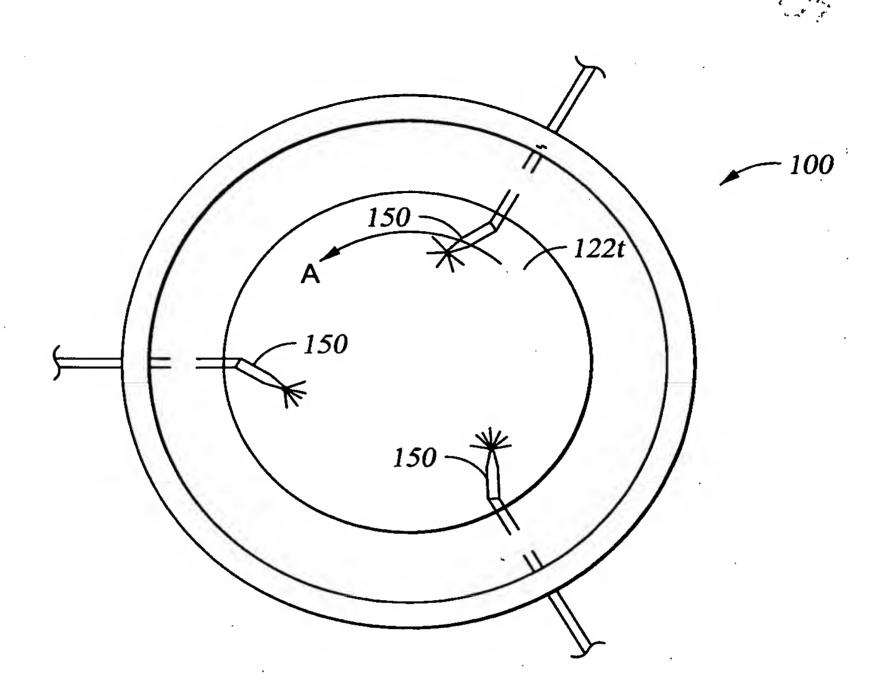


Fig. 3

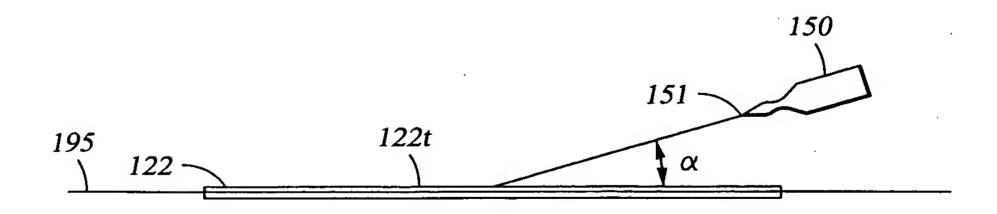


Fig. 4

REPLACEMENT SHEET AMAT/6060/CMP/ECP/RKK 10/043,561 ATTY DKT. No.: U.S. SERIAL No.: CONFIRMATION: 7947 FILED: **JANUARY 8, 2002** APPLICANT: APPLIED MATERIALS, INC.
SYSTEM FOR PLANARIZING METAL CONDUCTIVE LAYERS TITLE: INVENTOR: OLGADO, ET AL. SHEET 4 OF 10 4/10 160 180 152 106 108 122e 122b

REPLACEMENT SHEET AMAT/6060/CMP/ECP/RKK

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CONFIRMATION: 7947

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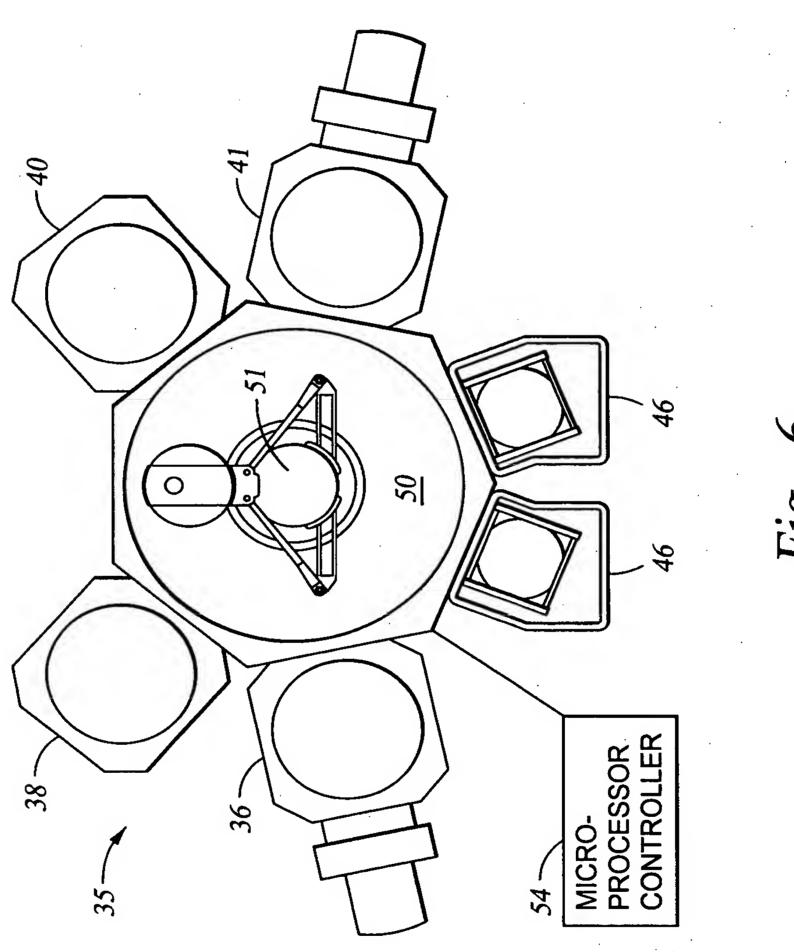
INVENTOR:

10/043,561 CONFIRMATION: 79
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REPLACEMENT SHEET AMAT/6060/CMP/ECP/RKK

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INVENTOR:

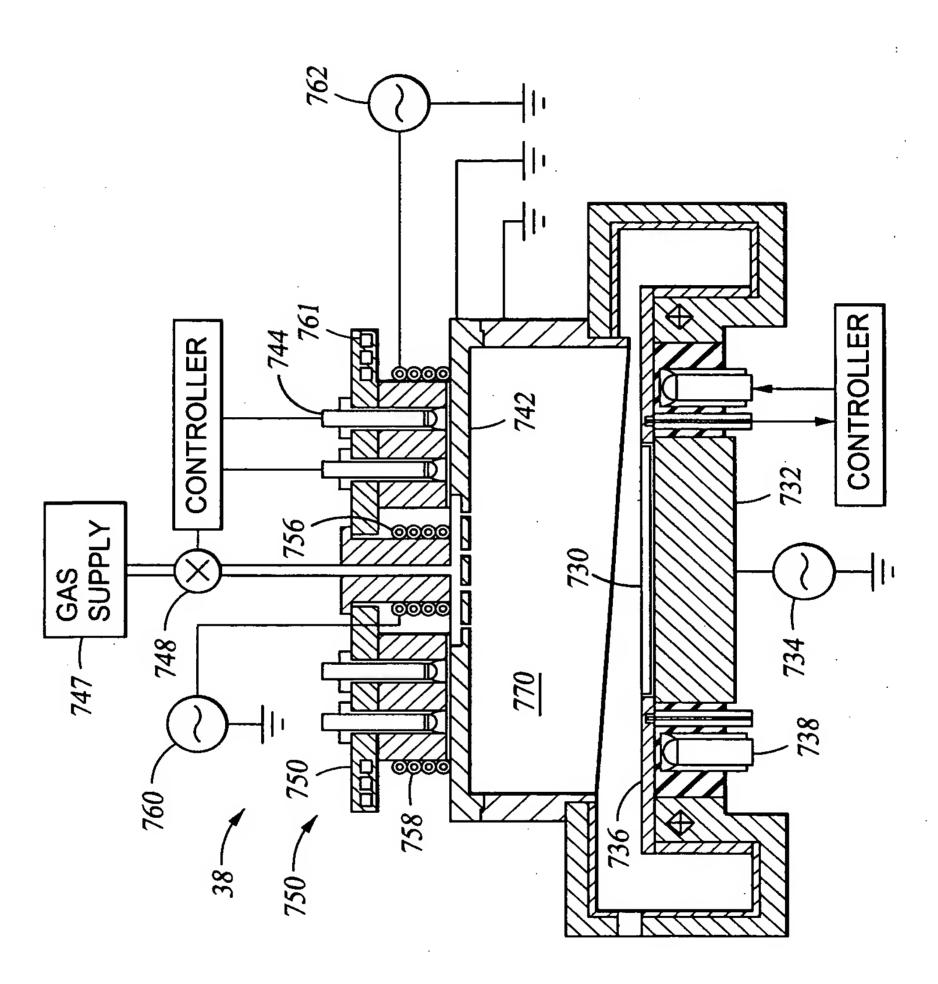
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System For Planarizing Metal Conductive Layers

OLGADO, ET AL.

SHEET 6 OF 10





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REPLACEMENT SHEET

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OLGADO, ET AL.

SHEET 7 OF 10

CONFIRMATION: 7947

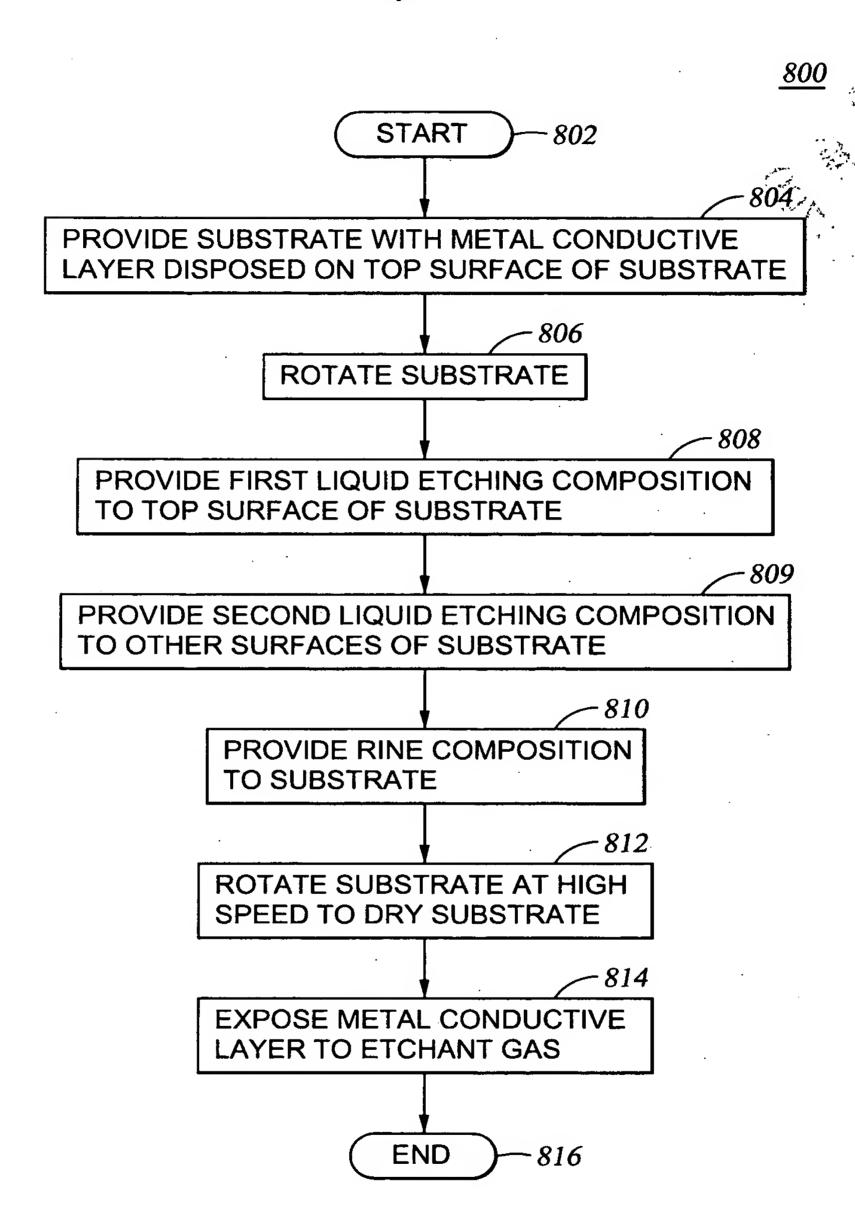


Fig. 8

REPLACEMENT SHEET

AMAT/6060/CMP/ECP/RKK ATTY DKT. No.: U.S. SERIAL NO.: 10/043,561

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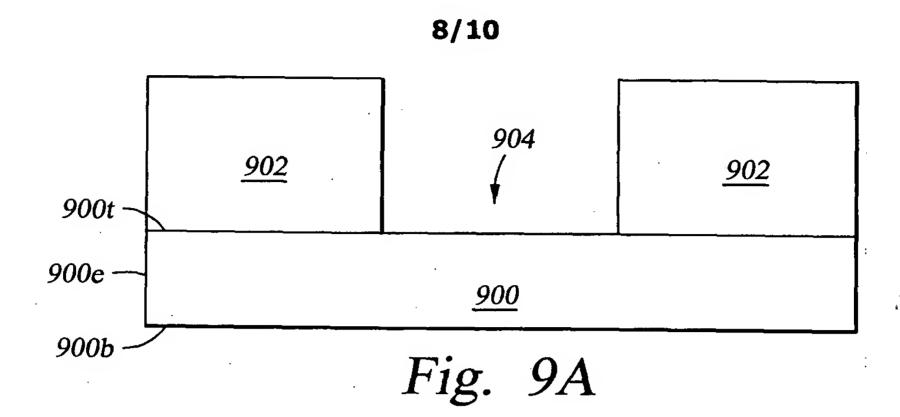
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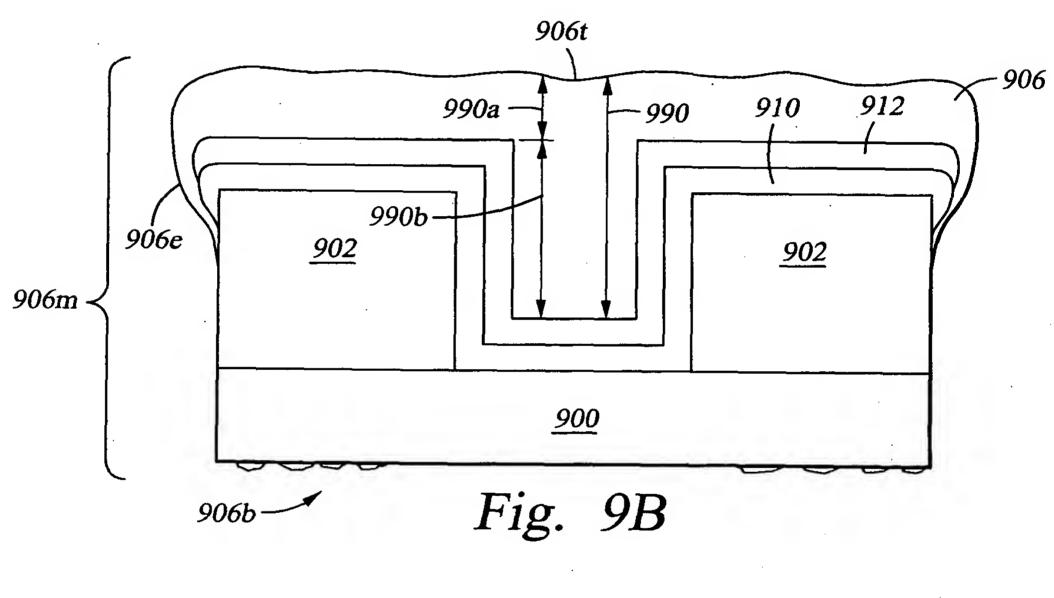
INVENTOR:

SYSTEM FOR PLANARIZING METAL CONDUCTIVE LAYERS OLGADO, ET AL.

SHEET 8 OF 10

CONFIRMATION: 7947





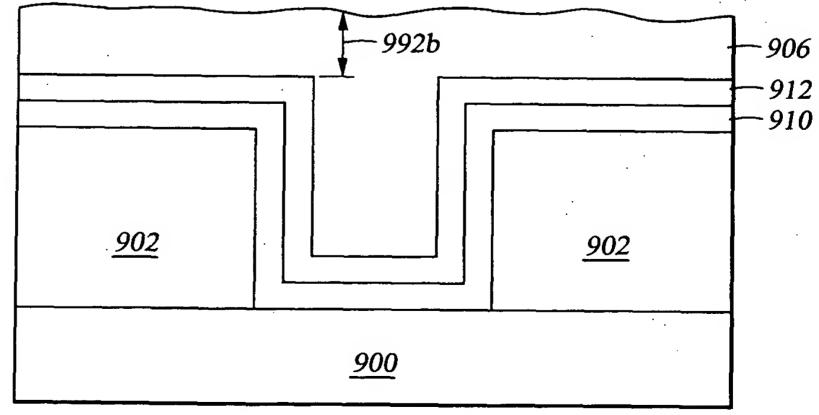


Fig. 9C

REPLACEMENT SHEET ATTY DKT. No.: U.S. SERIAL No.: AMAT/6060/CMP/ECP/RKK 10/043,561 CONFIRMATION: 7947 **JANUARY 8, 2002** FILED: APPLICANT: APPLIED MATERIALS, INC. SYSTEM FOR PLANARIZING METAL CONDUCTIVE LAYERS TITLE: OLGADO, ET AL. INVENTOR: SHEET 9 OF 10 9/10 1002 1002 1000e 1000 Fig. 10A 1006t 1006 1012 1010 1090a 1090 1006e 1090b 1002 1002 1006m <u>1000</u> Fig. 1006b - 1006 1092b

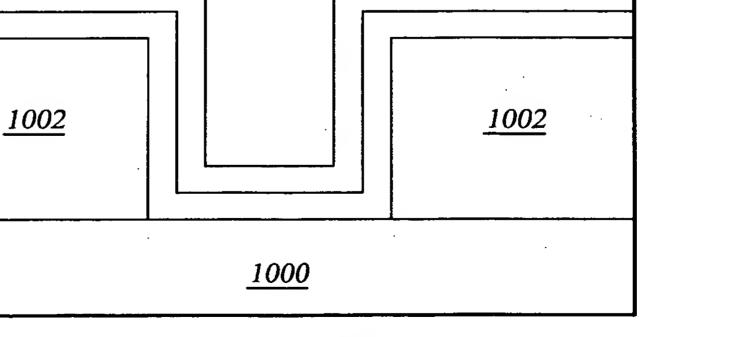


Fig. 10C

ATTY DKT. No.: U.S. SERIAL NO.: FILED:

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REPLACEMENT SHEET AMAT/6060/CMP/ECP/RKK 10/043,561 JANUARY 8, 2002

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CONFIRMATION: 7947

TITLE: INVENTOR:

SYSTEM FOR PLANARIZING METAL CONDUCTIVE LAYERS

OLGADO, ET AL.

SHEET 10 OF 10



10/10

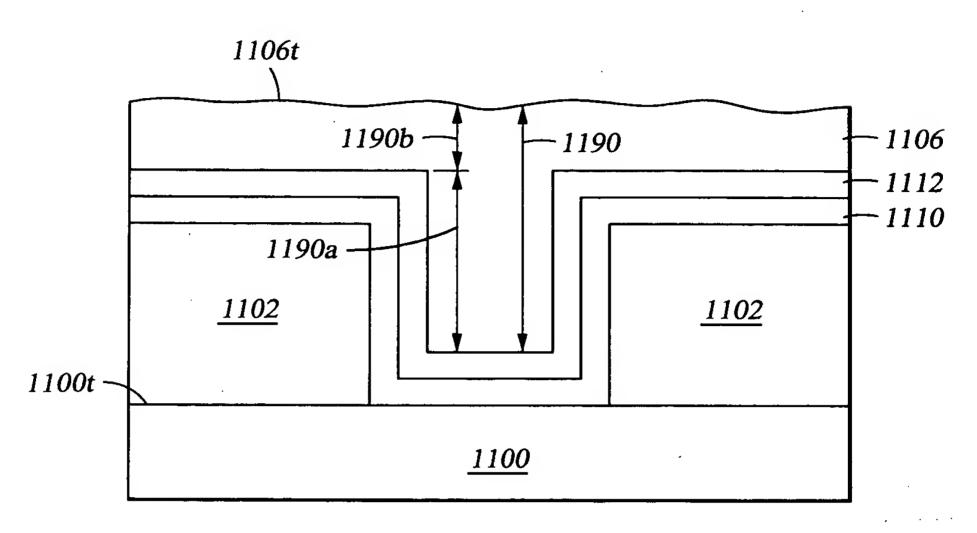


Fig. 11A

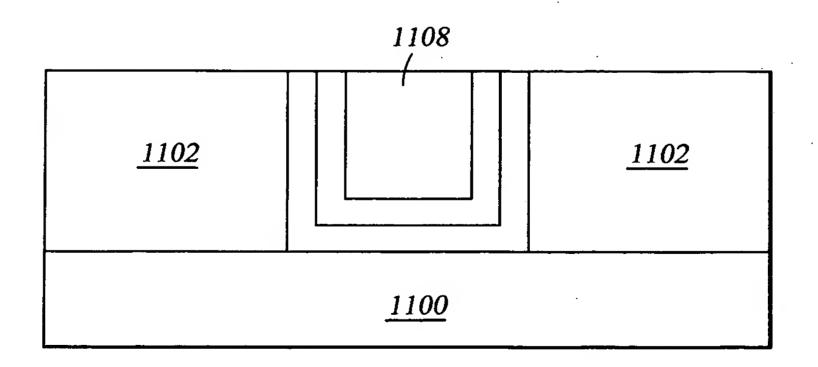


Fig. 11B